

# Review of TPC Detector R&D for CEPC CDR

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# Outline

- Motivation in CEPC CDR
- TPC detector module and prototype
- FEE electronics ASIC chip
- Summary

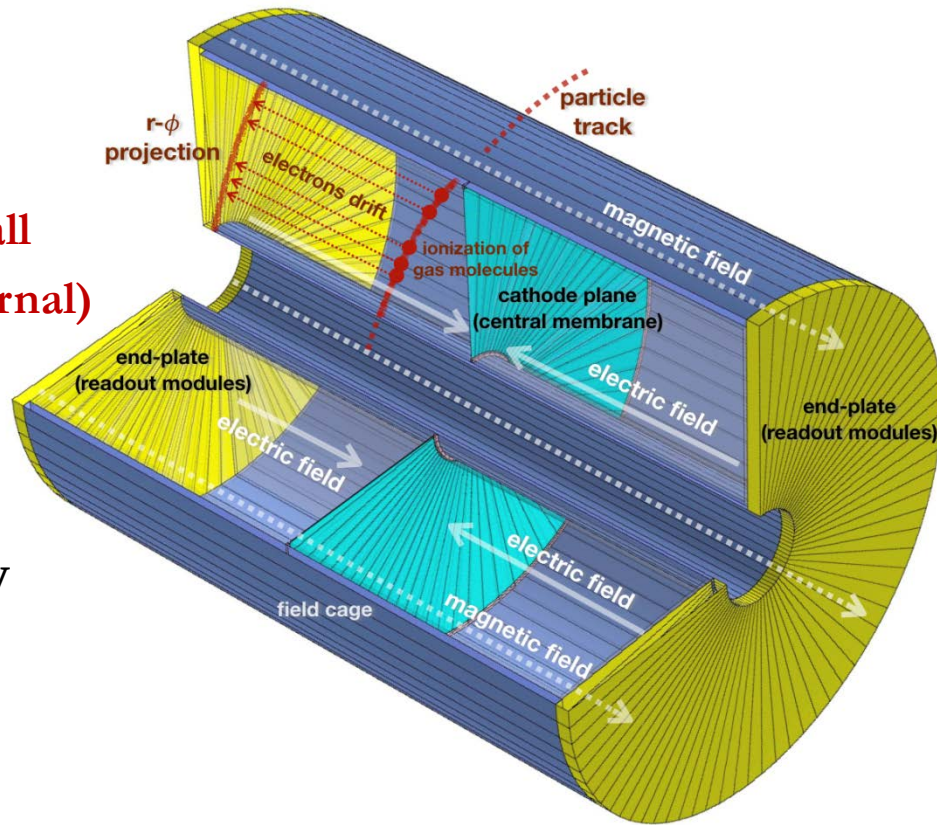
- Motivation in CEPC CDR

# TPC requirements for collider concept

**TPC could be as one tracker detector option for CEPC**, 1M ZH events in 10yrs  $E_{\text{cm}} \approx 240$  GeV, luminosity  $\sim 2 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$ , can also run at the Z-pole

## TPC detector concept:

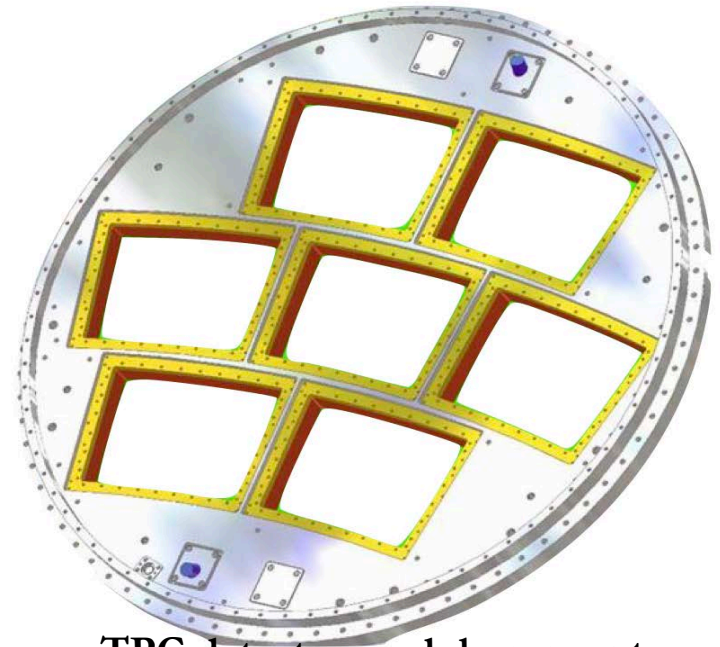
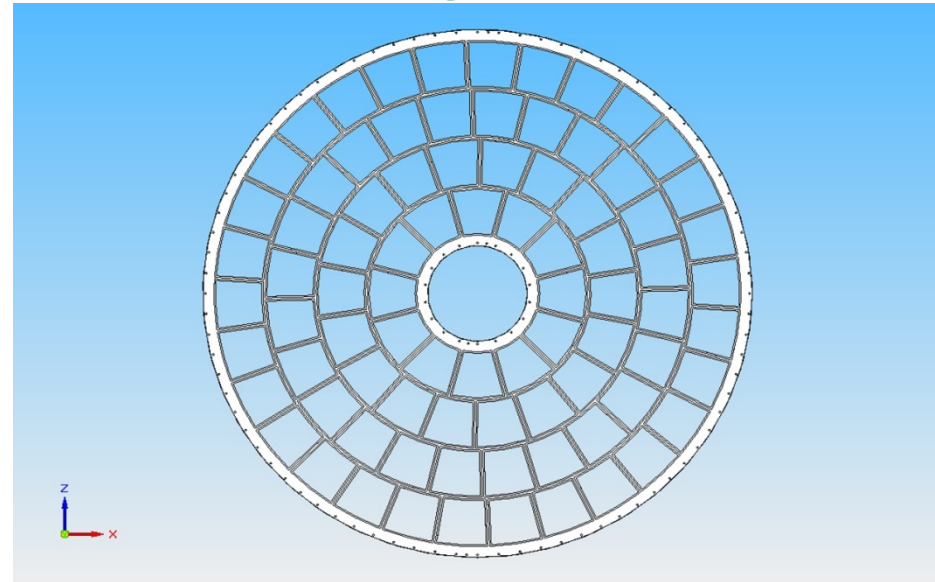
- ❑ Motivated by the H tagging and Z
- ❑  $\sim 3$  Tesla magnetic field
- ❑  $\sim 100 \mu\text{m}$  position resolution in  $r\phi$ 
  - ❑  $\sim 60 \mu\text{m}$  for zero drift,  $< 100 \mu\text{m}$  overall
  - ❑ Systematics precision ( $< 20 \mu\text{m}$  internal)
- ❑ Large number of 3D points ( $\sim 220$ )
- ❑ Distortion by IBF issues
- ❑  $dE/dx$  resolution:  $< 5\%$
- ❑ Tracker efficiency:  $> 97\%$  for  $p_T > 1 \text{ GeV}$
- ❑ 2-hit resolution in  $r\phi$  :  $\sim 2 \text{ mm}$
- ❑ Momentum resolution:  $\sim 10^{-4}/\text{GeV}/c$
- ❑ TPC material budget
  - ❑  $0.05 X_0$  including outer fieldcage in  $r$
  - ❑  $0.25 X_0$  for readout endcaps in  $z$



Overview of TPC detector concept

# TPC with MPGDs as readout / Advantage

- Higher accuracy  $< 100\text{mm}$  (Overall along the drift)
- **Better two track resolution**
- Full 3-D track reconstruction
- Precise  $dE/dX$
- **High magnetic field ( $>3\text{T}$ )**
- **Highly reduced  $E \times B$  effect**
- Large detectors by industrial process
- **Easy assembled using the modules**
- **Minimal material budget**
- Much higher Ion feed back suppression
- Drift time gives the longitudinal coordinate



TPC detector module concept - 3 -

# CEPC Detector for CDR

**Baseline design parameters**

## Feasibility & Optimized Parameters

✓ Feasibility analysis: TPC and Passive Cooling Calorimeter is valid for CEPC

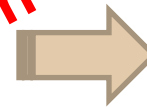
|                       | CEPC_v1<br>(~ ILD) | Optimized<br>(Preliminary) | Comments                                                                                                          |
|-----------------------|--------------------|----------------------------|-------------------------------------------------------------------------------------------------------------------|
| Track Radius          | 1.8 m              | $\geq 1.8$ m               | Requested by Br(H $\rightarrow$ di muon) measurement                                                              |
| <b>B Field</b>        | <b>3.5 T</b>       | <b>3 T</b>                 | <b>Requested by MDI</b>                                                                                           |
| <b>ToF</b>            | -                  | <b>50 ps</b>               | <b>Requested by pi-Kaon separation at Z pole</b>                                                                  |
| ECAL Thickness        | 84 mm              | 84(90) mm                  | 84 mm is optimized on Br(H $\rightarrow$ di photon) at 250 GeV;                                                   |
| ECAL Cell Size        | 5 mm               | 10 – 20 mm                 | Passive cooling request ~ 20 mm. 10 mm should be highly appreciated for EW measurements – need further evaluation |
| ECAL NLayer           | 30                 | 20 – 30                    | Depends on the Silicon Sensor thickness                                                                           |
| <b>HCAL Thickness</b> | <b>1.3 m</b>       | <b>1 m</b>                 | -                                                                                                                 |
| <b>HCAL NLayer</b>    | <b>48</b>          | <b>40</b>                  | Optimized on Higgs event at 250 GeV;                                                                              |

# Three key issue questions in CEPC CDR

## ■ Occupancy: at inner diameter

- ❑ Low occupancy
- ❑ Overlapping tracks
- ❑ Background at IP

Simulation

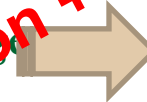


TPC as one option for  
CPEC **YES** or **NO**?

## ■ Ion Back Flow

- ❑ Continuous beam structure
- ❑ Long working time with low discharge possibility
- ❑ Necessary to fully suppress the space charge produced by ion back flow from the amplification gap

Simulation + R&D

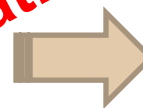


To control **IONS**?  
To reduce distortion

## ■ Calibration and alignment

- ❑ Complex MDI design
- ❑ Laser calibration system

Simulation + R&D



~**100um** positron  
resolution with calibration?



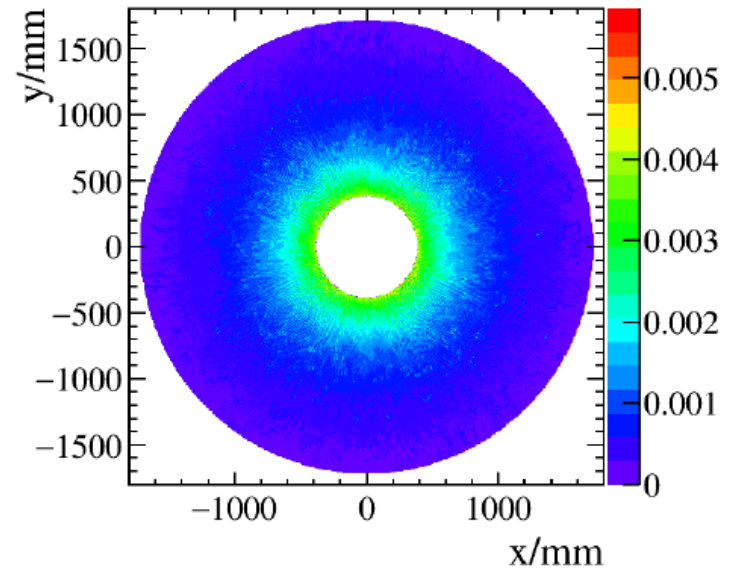
# High rate at Z pole

- ❑ Voxel occupancy
  - ❑ The number of voxels /signal
  - ❑ 9 thousand Z to qq events
  - ❑ 60 million hits are generated in sample
  - ❑ 4000-6000 hits/(Z to qq) in TPC volume
  - ❑ Average hit density: 6 hits/mm<sup>2</sup>
  - ❑ Peak value of hit density: 6 times
  - ❑ Voxel size: 1mm × 6mm × 2mm
  - ❑  $1.33 \times 10^{14}$  number of voxels/s @DAQ/40MHz
  - ❑ Average voxel occupancy:  $1.33 \times 10^{-8}$
  - ❑ Voxel occupancy at TPC inner most layer:  $\sim 2 \times 10^{-7}$
  - ❑ Voxel occupancy at TPC inner inner most layer :  $\sim 2 \times 10^{-5}$  @FCCee benchmark luminosity

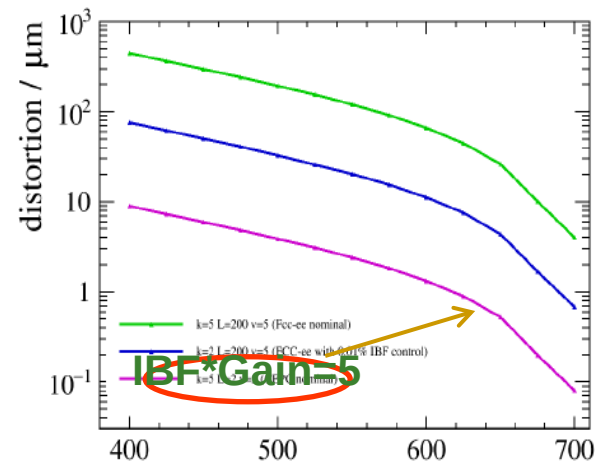
The voxel occupancy takes its maximal value between  $2 \times 10^{-5}$  to  $2 \times 10^{-7}$ , which is safety for the Z pole operation.

[ArXiv: 1704.04401](https://arxiv.org/abs/1704.04401)

Mingrui, Manqi, Huirong



Hit map on X-Y plan for Z to qq events



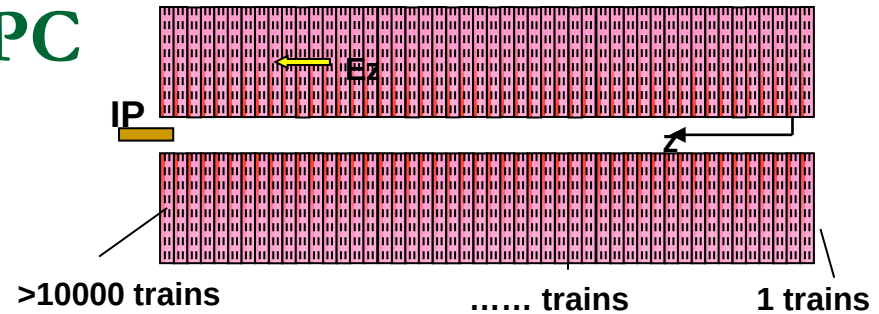
Distortion of as a function of electron initial r position



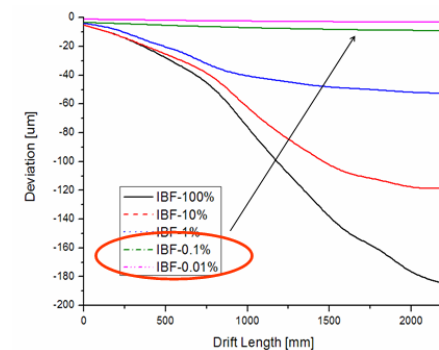
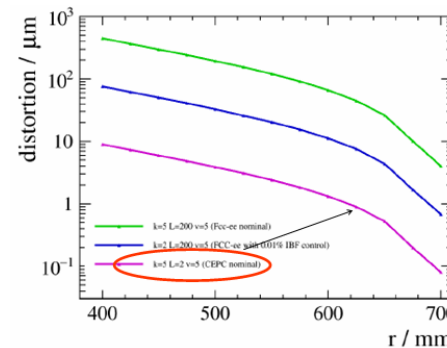
# Technical challenges for TPC

## Ion Back Flow and Distortion :

- ❑  $\sim 100 \mu\text{m}$  position resolution in  $r\phi$
- ❑ Distortions by the primary ions at CEPC are negligible
- ❑ More than 10000 discs co-exist and distorted the path of the seed electrons
- ❑ The ions have to be cleared during the  $\sim \mu\text{s}$  period continuously
- ❑ Continuous device for the ions
- ❑ Long working time



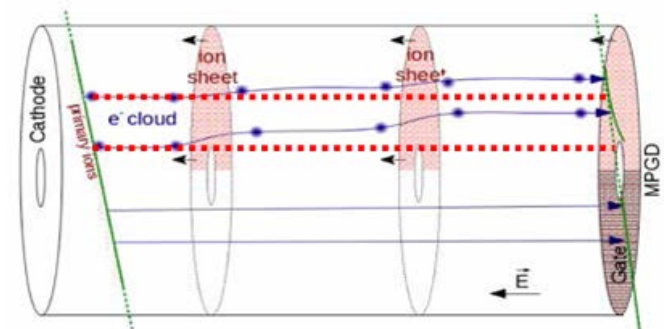
Amplification ions @CEPC



## Calibration and alignment:

- ❑ Systematics precision ( $< 20 \mu\text{m}$  internal)
- ❑ Geometry and mechanic of chamber
- ❑ Modules and readout pads
- ❑ Track distortions due to space charge effects of positive ions

## Evaluation of track distortions



Ions backflow in drift volume for distortion

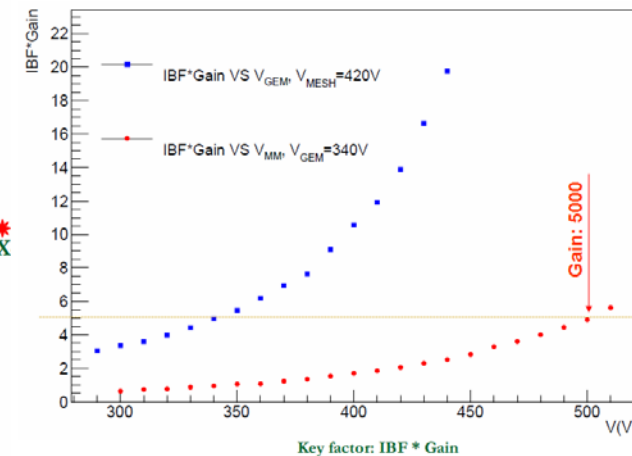
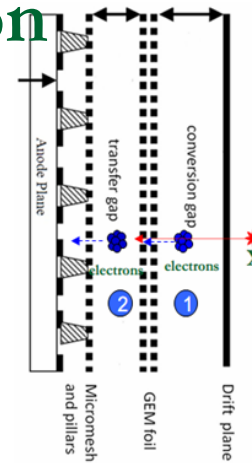
# Options of technical solution

## Continuous IBF module:

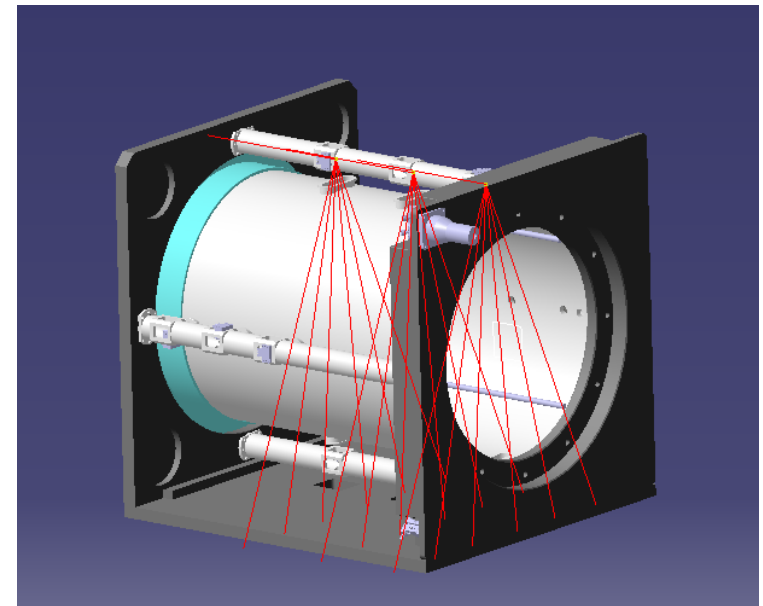
- ❑ **Gating device may be used for Higgs run**
- ❑ **Open and close time of gating device for ions:  $\sim \mu\text{s}$ -ms**
- ❑ **No Gating device option for Z-pole run**
- ❑ **Continuous Ion Back Flow due to the continuous beam structure**
- ❑ **Low discharge and spark possibility**

## Laser calibration system:

- ❑ **Laser calibration system for Z-pole run**
- ❑ **The ionization in the gas volume along the laser path occurs via two photon absorption by organic impurities**
- ❑ **Calibrated drift velocity, gain uniformity, ions back in chamber**
- ❑ **Calibration of the distortion**
- ❑ **Nd:YAG laser device@266nm**



Continuous IBF prototype and IBF  $\times$  Gain

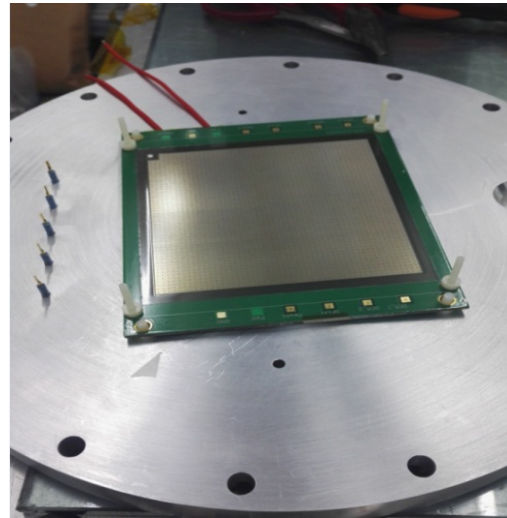
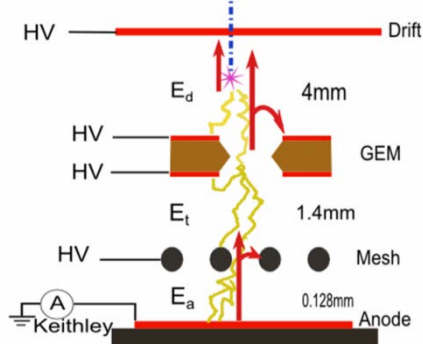


TPC prototype integrated with laser system

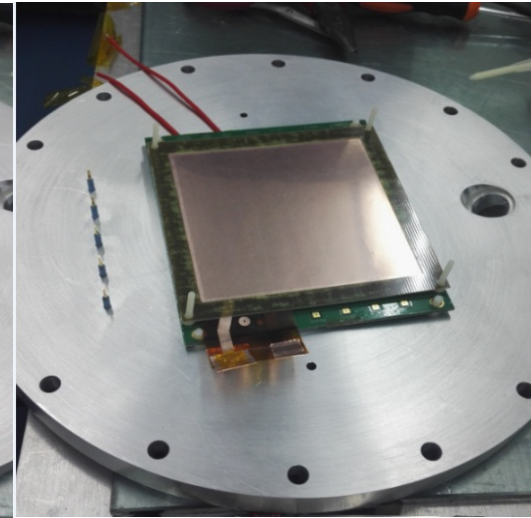
- Ions backflow reduced
- TPC detector module R&D
  - Combination detector
  - Discharge for IBF

# Test of the new module

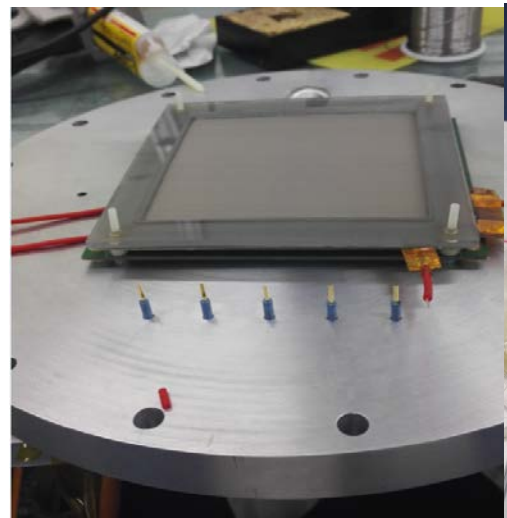
- ❑ Test with GEM-MM module
  - ❑ New assembled module
  - ❑ Active area:  $100\text{mm} \times 100\text{mm}$
  - ❑ X-tube ray and  $^{55}\text{Fe}$  source
  - ❑ Bulk-Micromegas from Saclay
  - ❑ Standard GEM from CERN
  - ❑ Additional UV light device
  - ❑ Avalanche gap of MM:  $128\mu\text{m}$
  - ❑ Transfer gap:  $2\text{mm}$
  - ❑ Drift length:  $2\text{mm} \sim 200\text{mm}$
  - ❑ Mesh: 400LPI



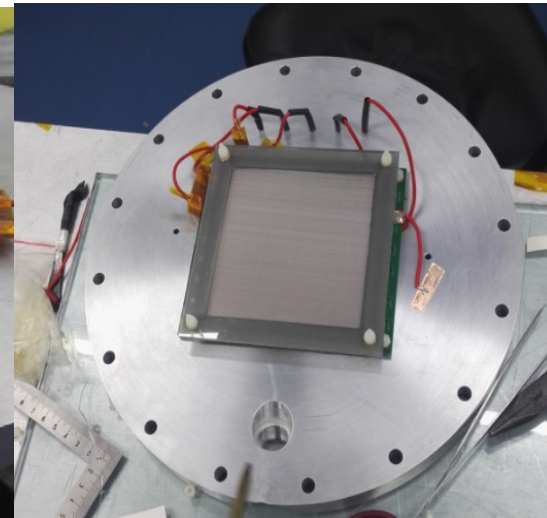
Micromegas(Saclay)



GEM(CERN)



Cathode with mesh



GEM-MM Detector

# GEM+MM@CEPC R&D

**e<sup>+</sup>e<sup>-</sup> machine**

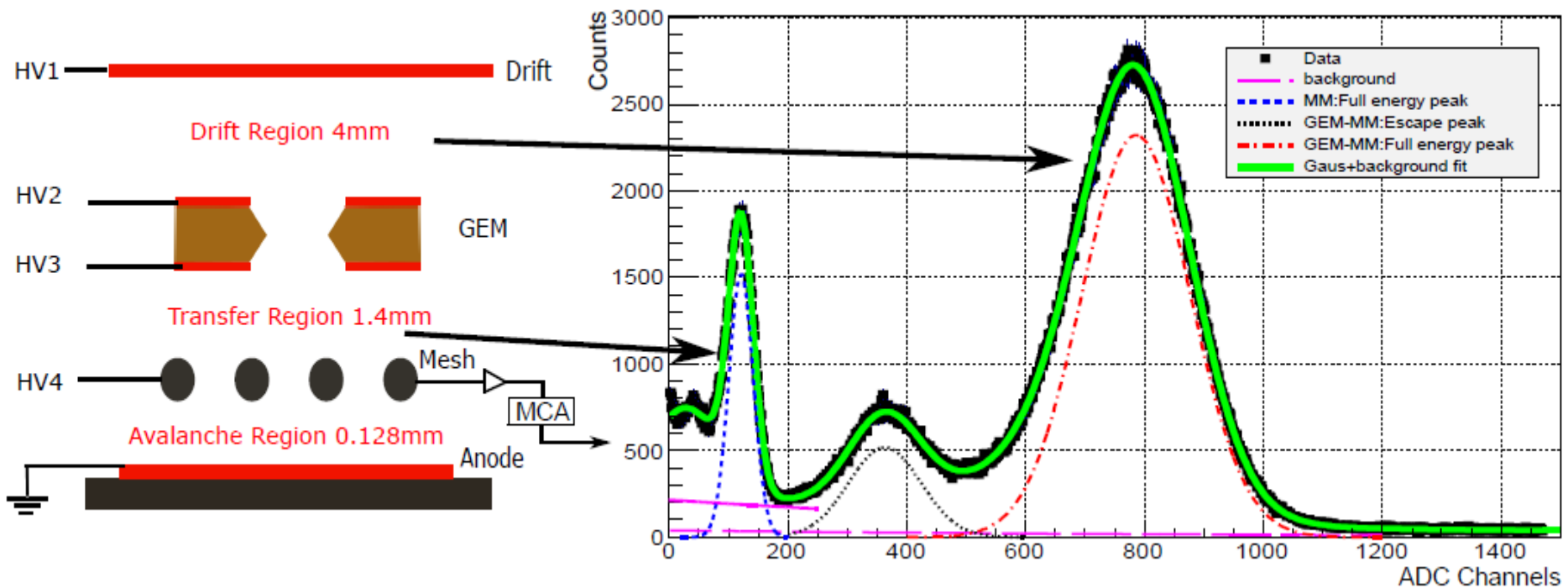
**Primary  $N_{\text{eff}}$  is small:  $\sim 30$**

**Pad size: 1mm  $\times$  6mm**

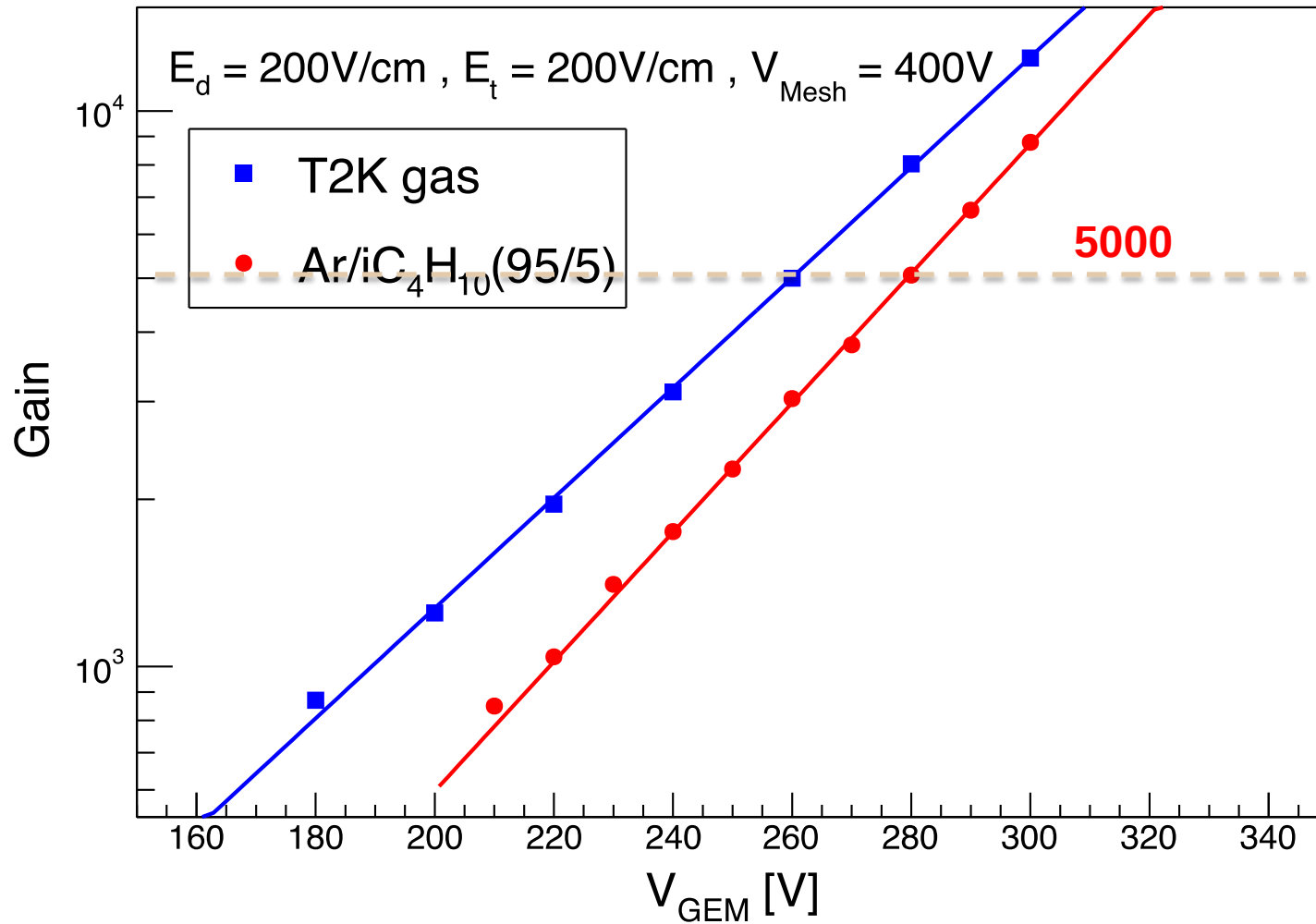
**Photo peak and escape peak are clear!**

**Good electron transmission.**

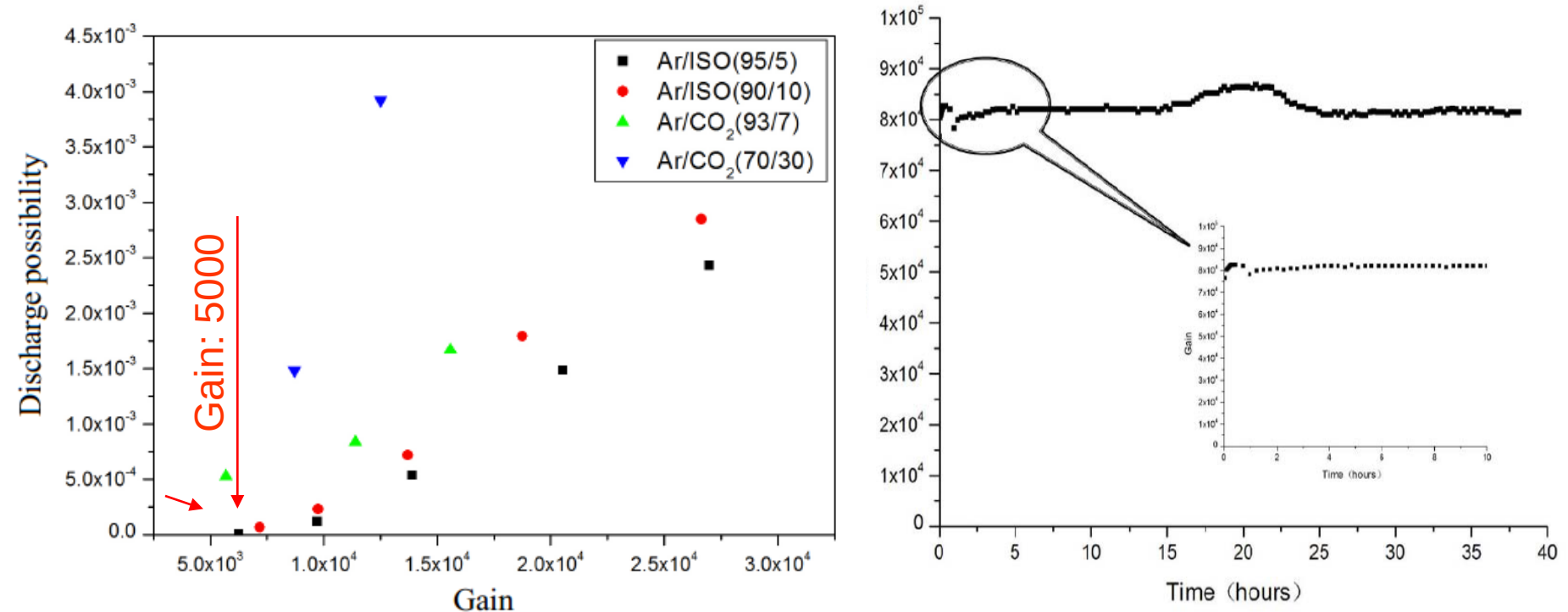
**Good energy resolution.**



# Gain of the hybrid structure detector



# Discharge and working time



- ❑ Test with Fe-55 X-ray radiation source
  - ❑ Discharge possibility could be mostly reduced than the standard Bulk-Micromegas
  - ❑ Discharge possibility of hybrid detector could be used at Gain~10000
  - ❑ To reduce the discharge probability more obvious than standard Micromegas
  - ❑ At higher gain, the module could keep the longer working time in stable



# Electrometer/High Resistance Meter

## Keithley 6517B

Electrometer/High Resistance Meter, 100aA  
- 20mA, 10 $\mu$ V - 200V, 100 $\Omega$  - 10P $\Omega$

Brand: Keithley

Model No: 6517B



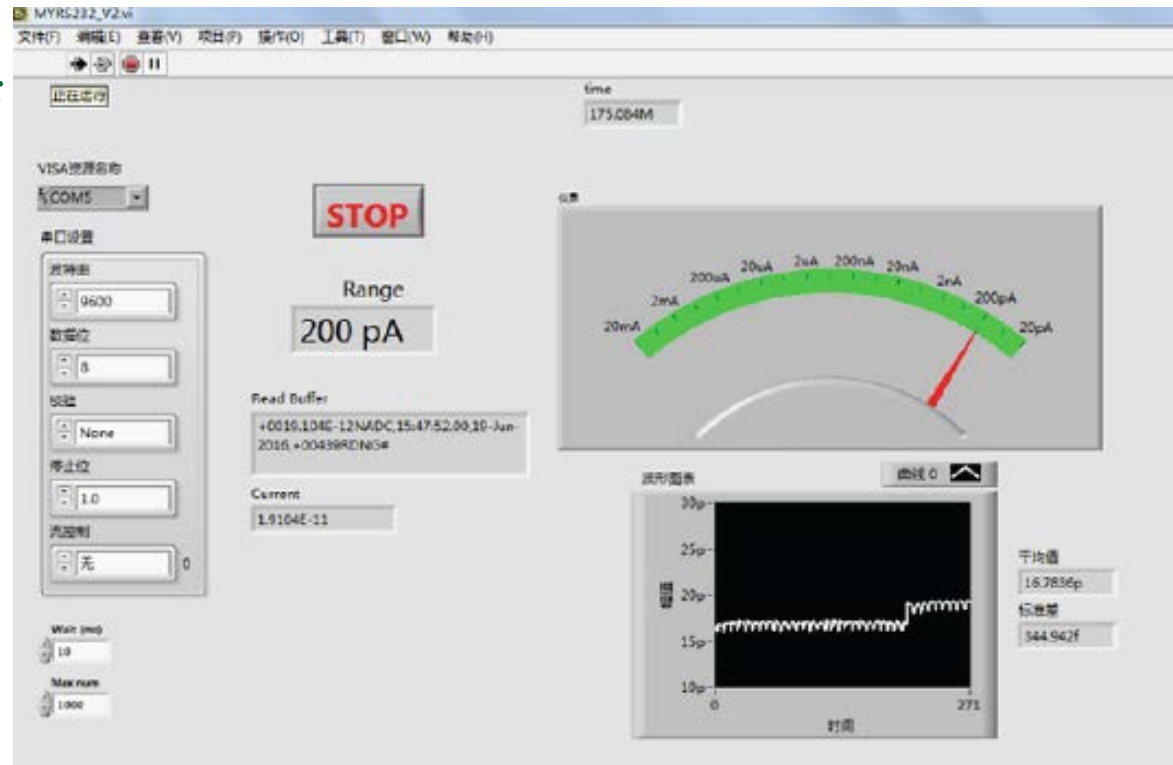
### Product Features:

- Measures resistances up to 10180
- 10aA (10 $\times$ 10-18A) current measurement resolution
- Less than 3fA input bias current
- 6 1/2-digit high accuracy measurement mode
- Less than 20 $\mu$ V burden voltage on the lowest current ranges
- Voltage measurements up to 200V with >200TO input impedance
- Built-in +/-1000V voltage source
- Unique alternating polarity voltage sourcing and measurement method for high resistance measurements
- Built-in test sequences for four different device characterization tests, surface and volume resistivity, surface insulation resistance, and voltage sweeping
- Optional plug-in scanner cards for testing up to 10 devices or material samples with one test setup



# Measurement of GEM-MM module

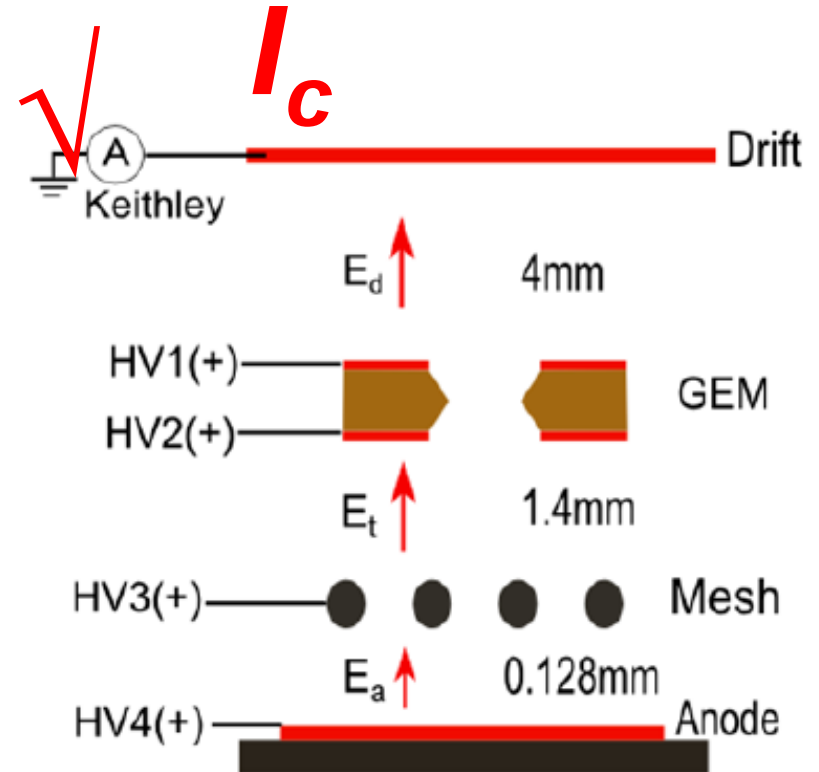
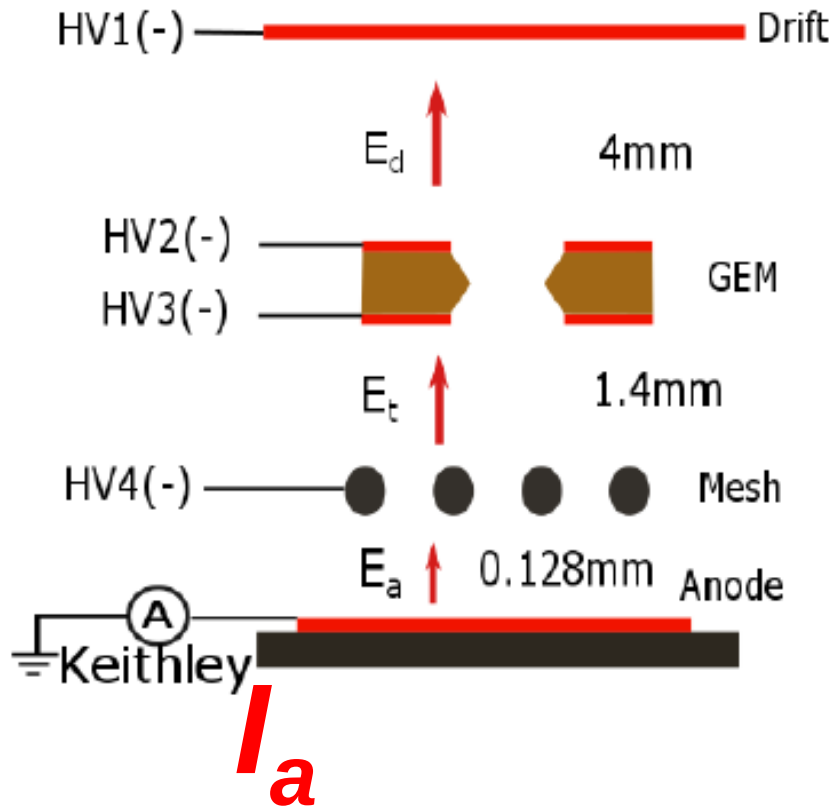
- ❑ Test with GEM-MM module
  - ❑ Keithley Electrometers for Ultra-Low Current Measurements: pA~mA
  - ❑ Keithley: 6517B
  - ❑ Test of cathode of the module
  - ❑ Test of readout anode of the module
  - ❑ Labview interface of the low current to make the record file automatically



Labview interface of the current with Keithley

$$IBF = \frac{I_C - I_P}{I_A}$$

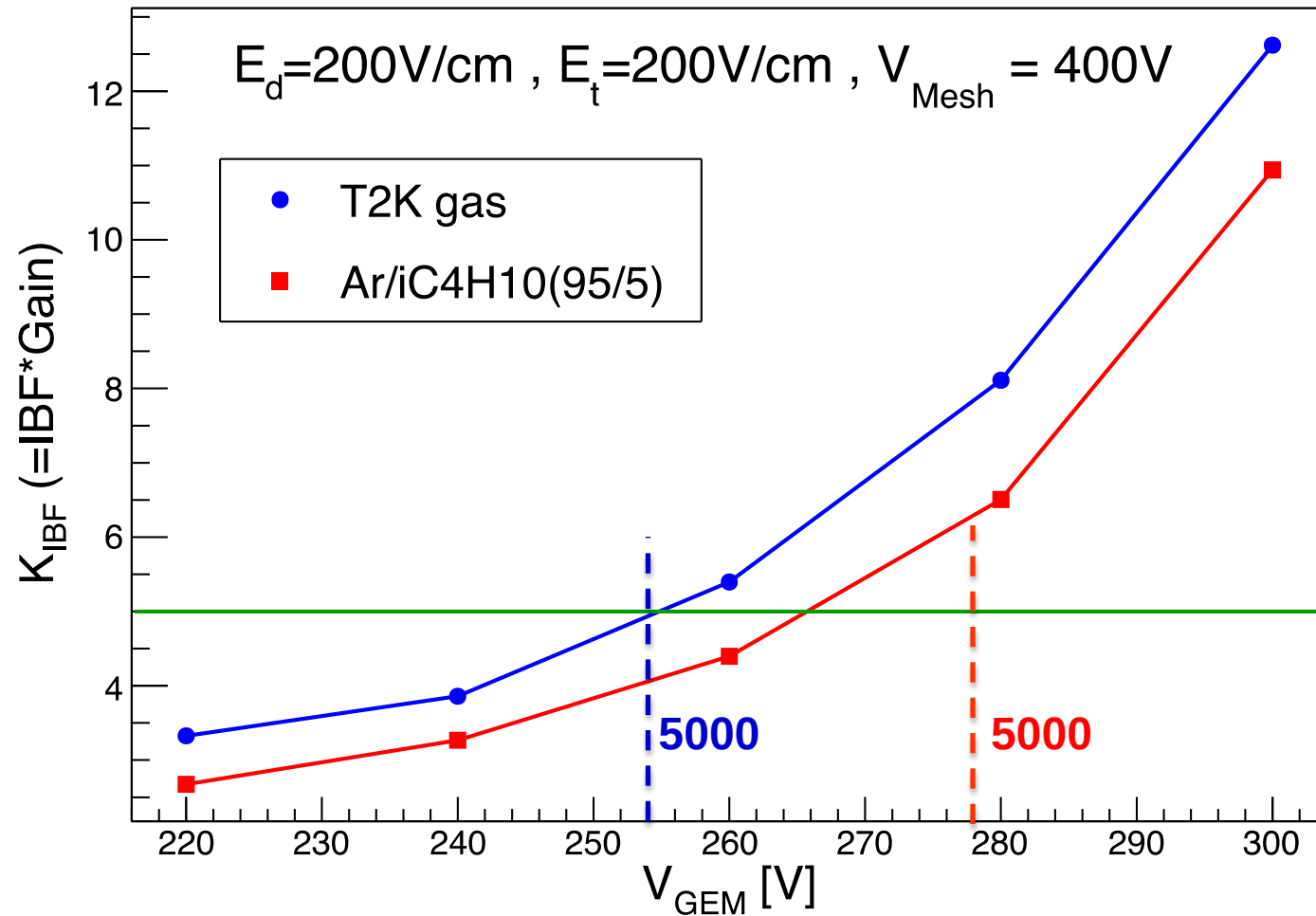
## Two steps



- Different polarity
- Same electric field
  - $E_d=E_d$ ;  $E_t=E_t$ ;  $E_a=E_a$

# Key IBF factor: $\text{IBF} \times \text{Gain}$

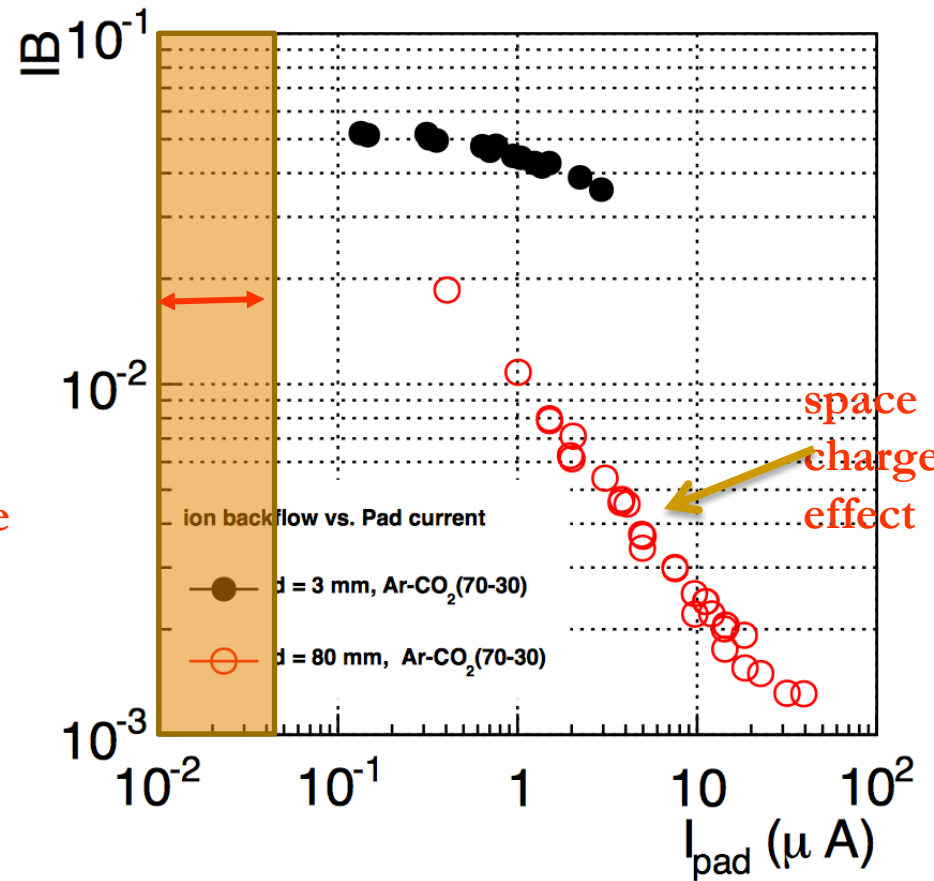
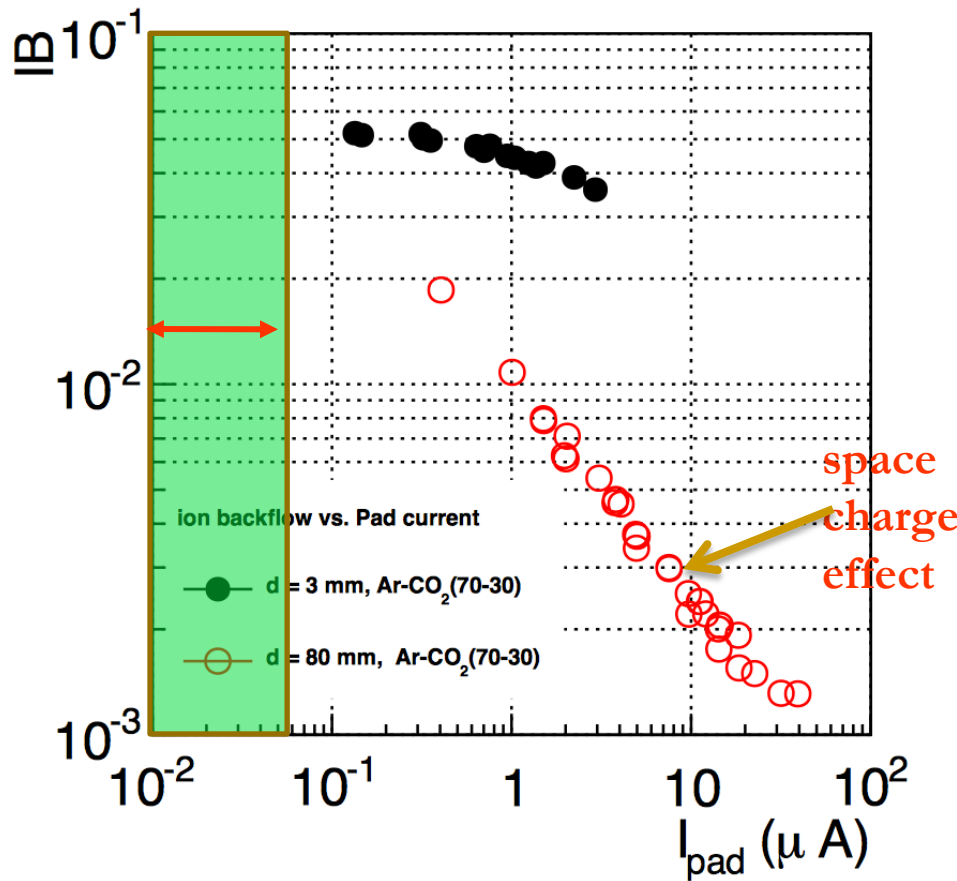
Preliminary results in 2018



- Space charge effect for IBF

# Check and answer- $I_{\text{pad}}$

Current of Pad is very low in our Exp.  
No space charge effect

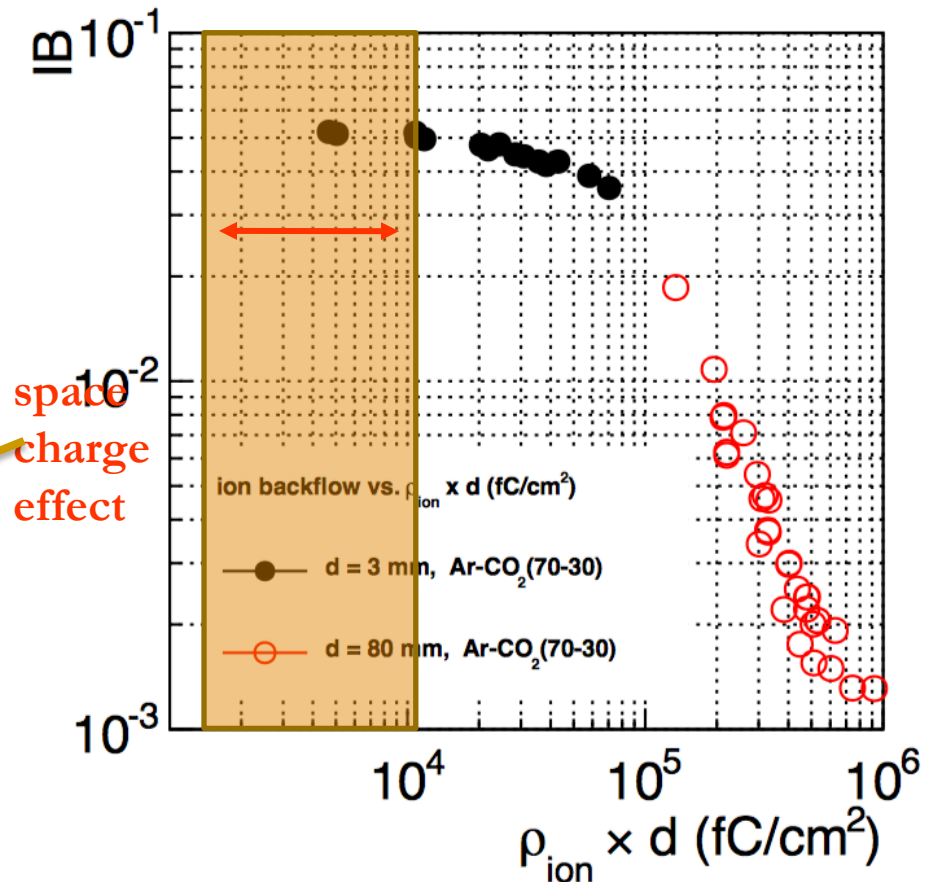
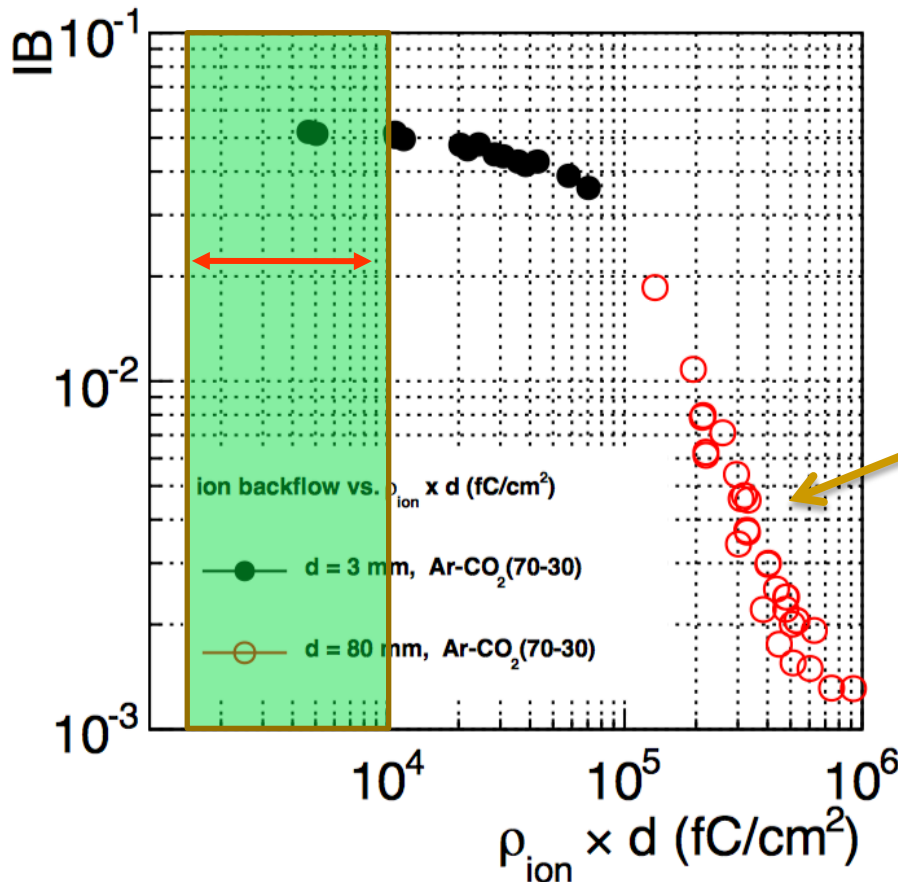


Green, T2K,  $E_t=200\text{V/cm}$ ,  $E_d=200\text{V/cm}$ ,  $V_{\text{mesh}}=400\text{V}$ ,  $V_{\text{Gem}}:30\sim300\text{V}$

Yellow, Ar/iso(95/5),  $E_t=200\text{V/cm}$ ,  $E_d=200\text{V/cm}$ ,  $V_{\text{mesh}}=400\text{V}$ ,  $V_{\text{Gem}}:30\sim300\text{V}$

Check and answer-  $\rho_{\text{ion}} \times d$

Current of Pad is very low in our Exp.  
No space charge effect



Green: T2K, Yellow: Ar/iso(95/5)

T2Kgas Ic: 4pA~59pA,  $\sim 10^3$  (fC/cm<sup>2</sup>)

Ar/iso gas Ic : 3.5pA~53pA,  $\sim 10^3$  (fC/cm<sup>2</sup>)



- Calibration (Drift velocity/Uniformity/Distortion)
- TPC detector prototype R&D
  - Signal of the 266nm laser beam @MPGD
  - Stability of the position @100um resolution
  - Stability of the energy @ASIC FEE

# Motivation of the TPC prototype

- Study and estimation of the distortion from the IBF and primary ions with the laser calibration system
- Main parameters
  - Drift length:  $\sim 510\text{mm}$ , Readout active area:  $200\text{mm} \times 200\text{mm}$
  - Integrated the laser calibration with 266nm
  - GEMs/Micromegas as the readout
  - Matched to assembled in the 1.0T PCMAG

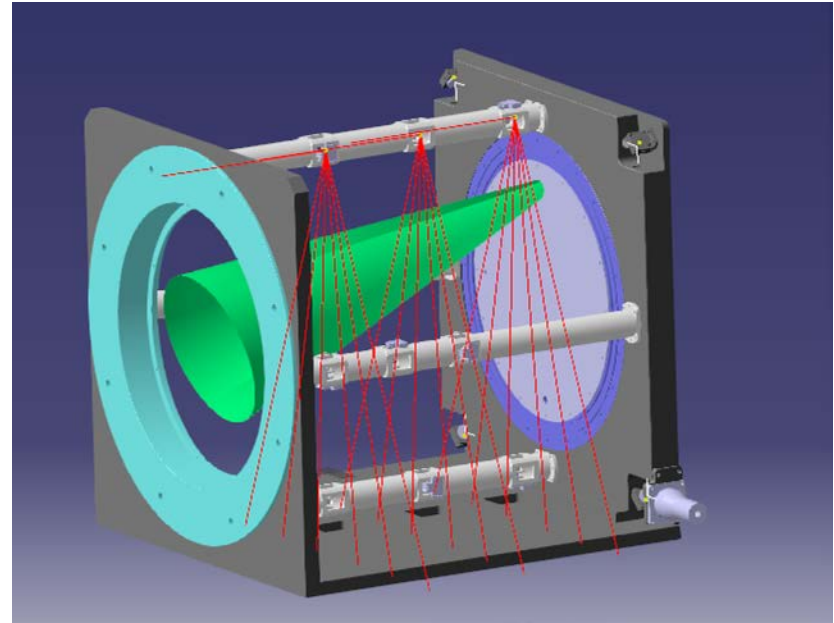
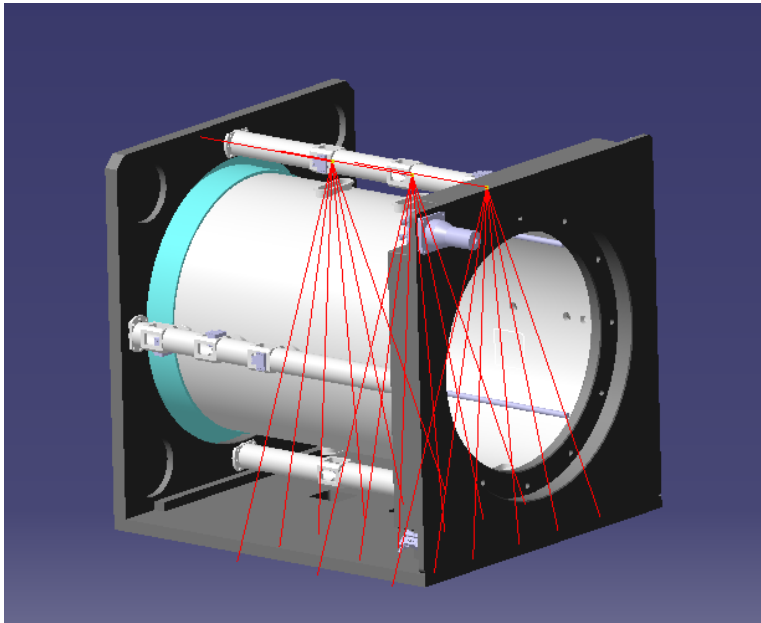
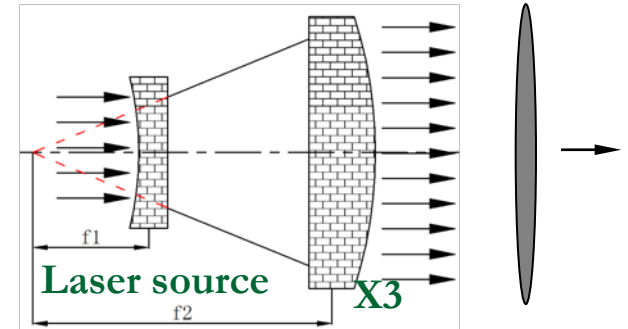


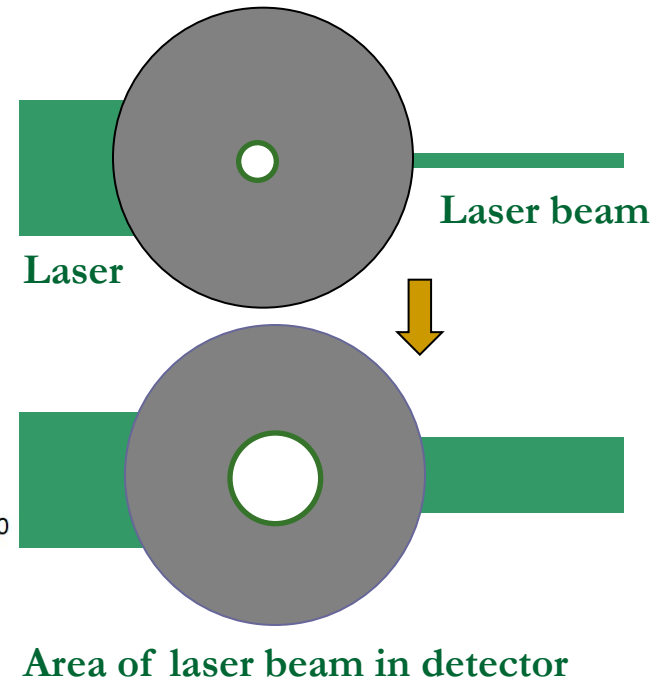
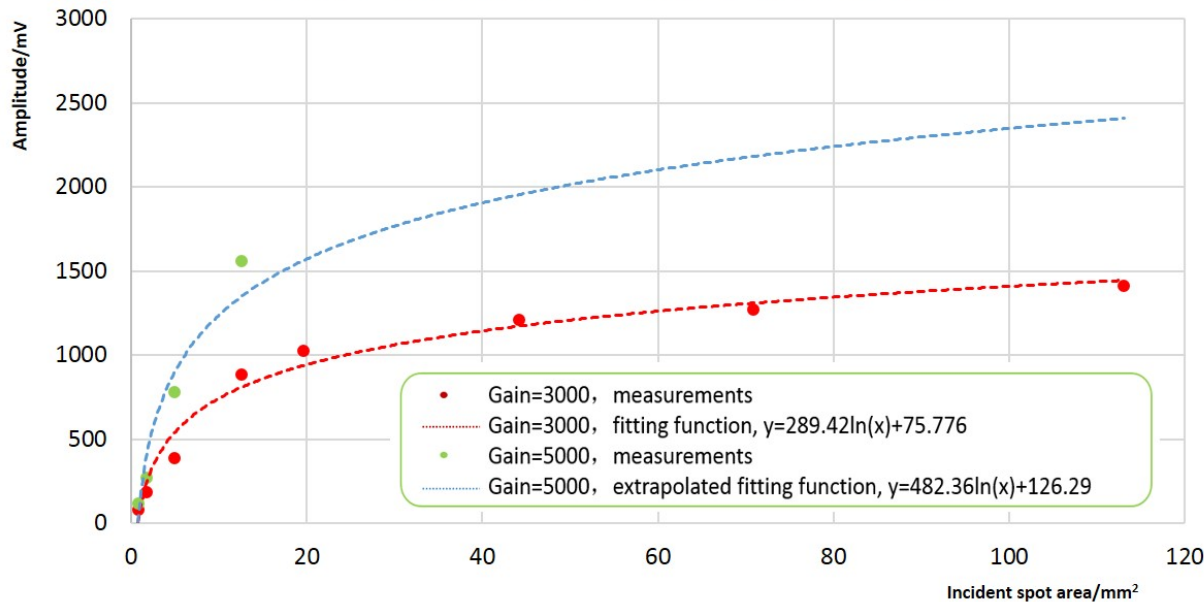
Diagram of the TPC prototype with the laser calibration system

# Collimator for the laser beam @ $\Phi 1 \sim \Phi 12\text{mm}$

- ❑ Laser beam with expander mirror:  $5\text{mm} \times 3$
- ❑ Primary laser power:  $170\mu\text{J}$
- ❑ Gain:  $\sim 3000/5000$



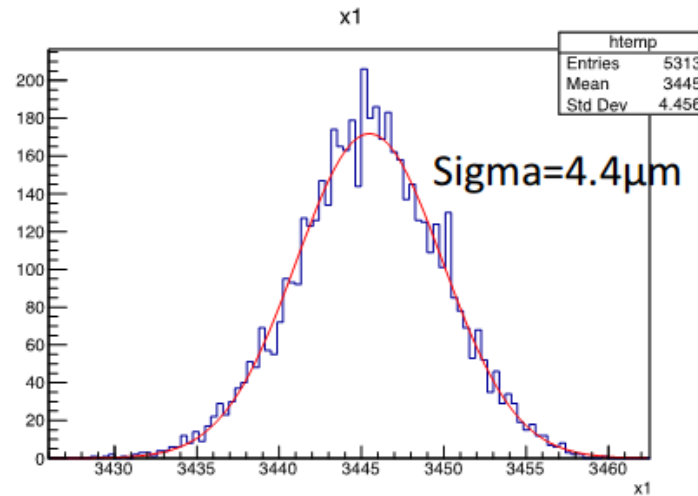
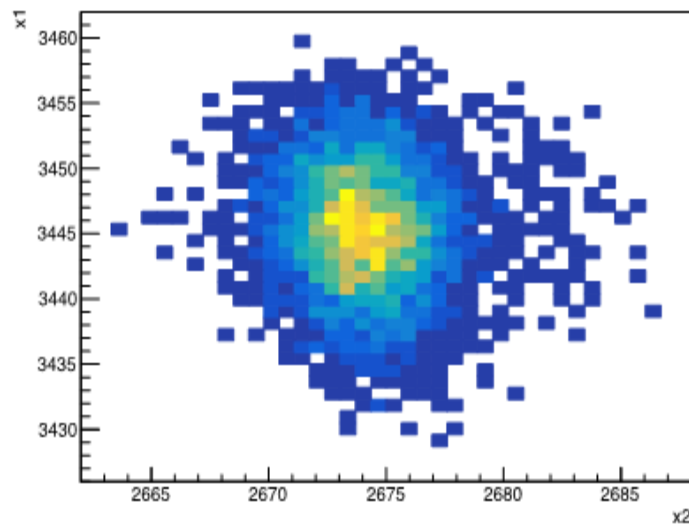
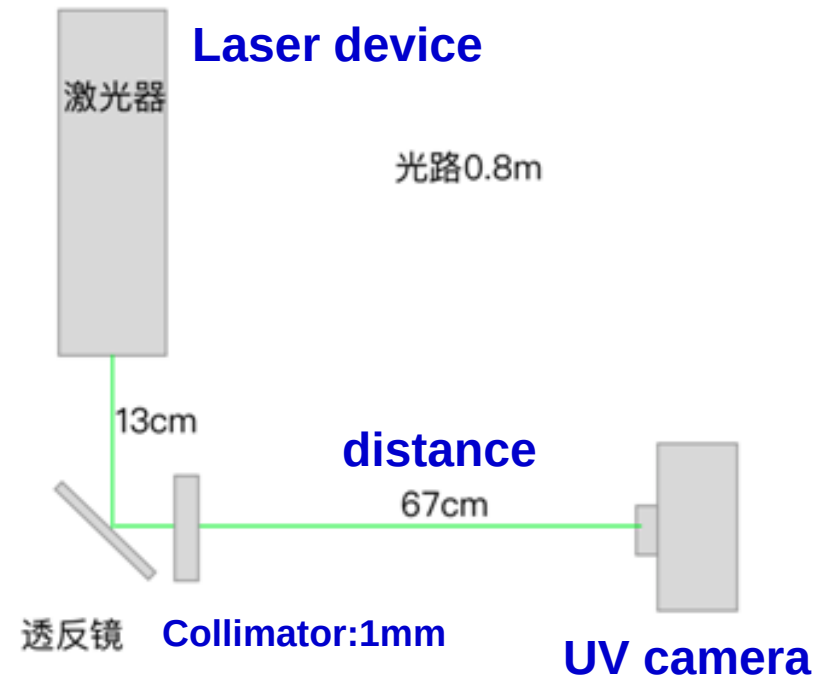
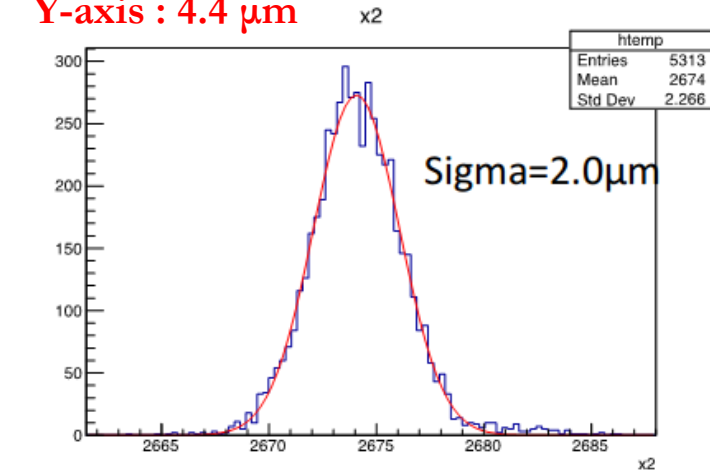
Signals of different laser beam size at specific gain



# Stability of the laser beam position

GOOD !

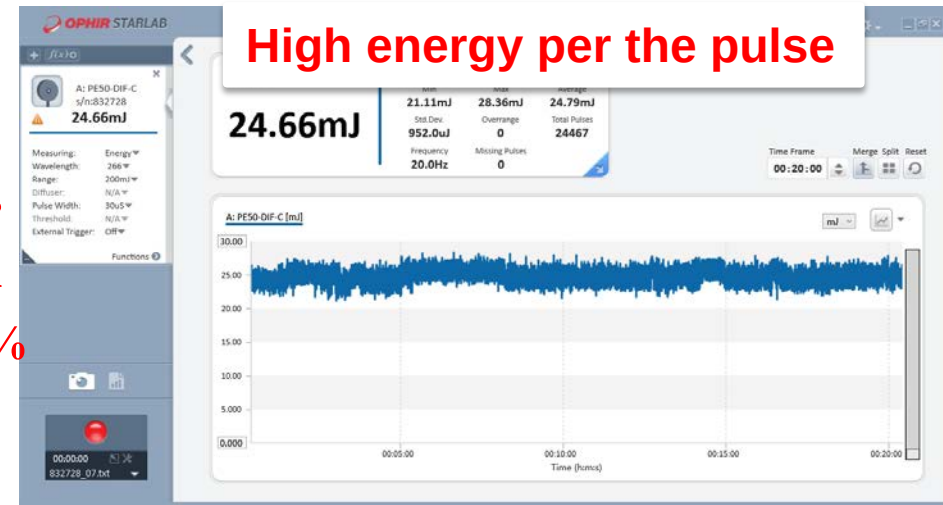
- Duration of measurement time: 10mins
- Stability of the laser beam energy
  - X-axis : 2.0  $\mu\text{m}$
  - Y-axis : 4.4  $\mu\text{m}$



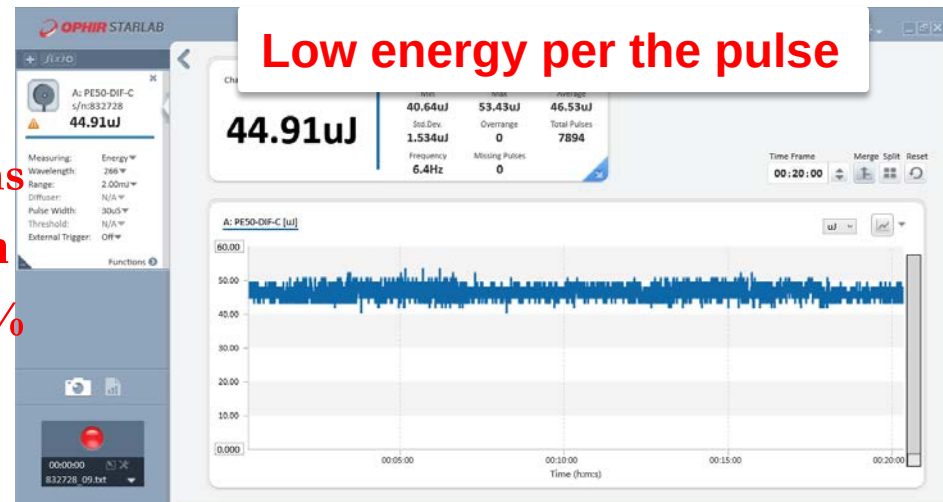
# Stability of the laser beam energy

GOOD !

- ❑ Duration of measurement time: 20mins
- ❑ Average of the energy: 24.79mJ/Φ5mm
- ❑ Stability of the laser beam energy: 3.84%

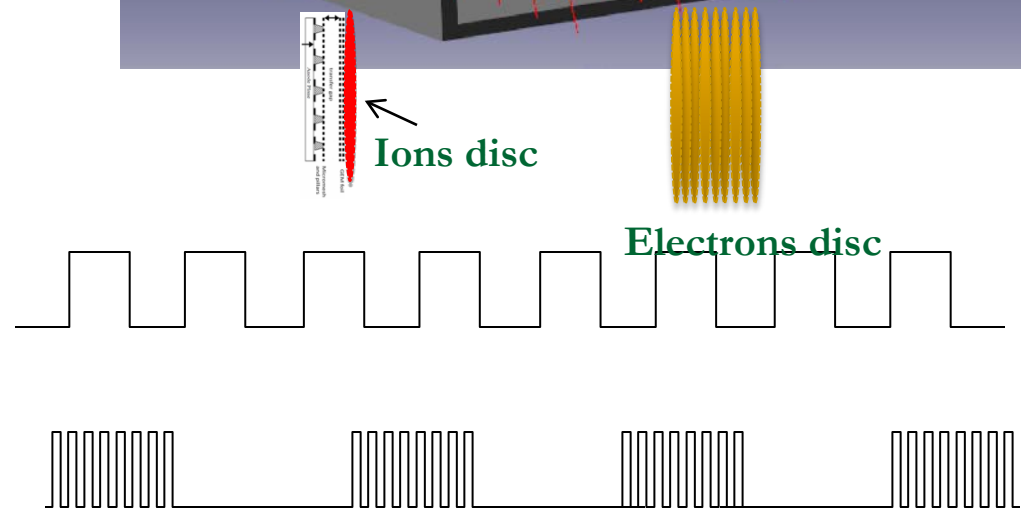
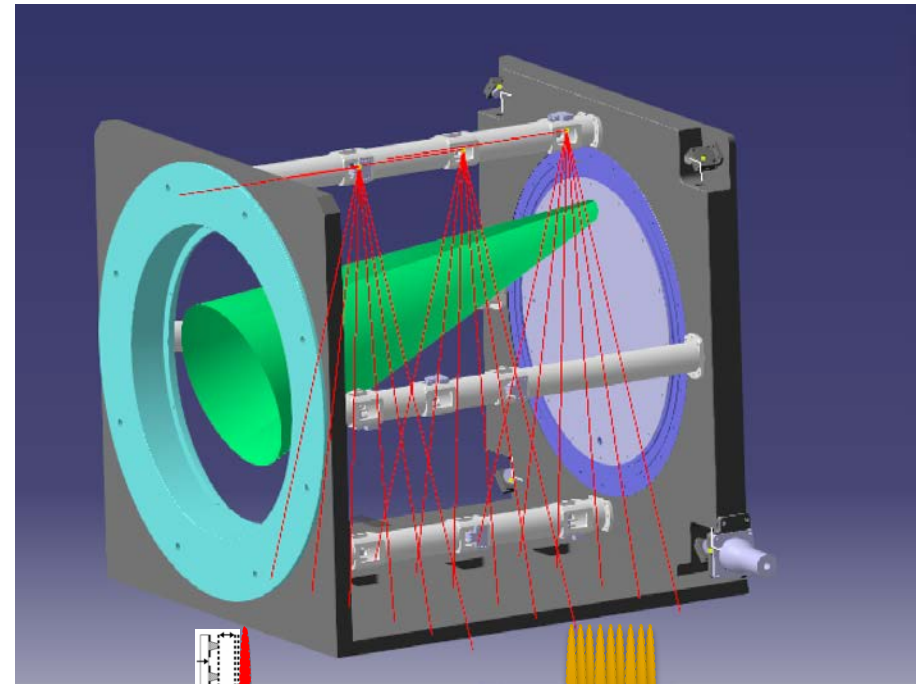
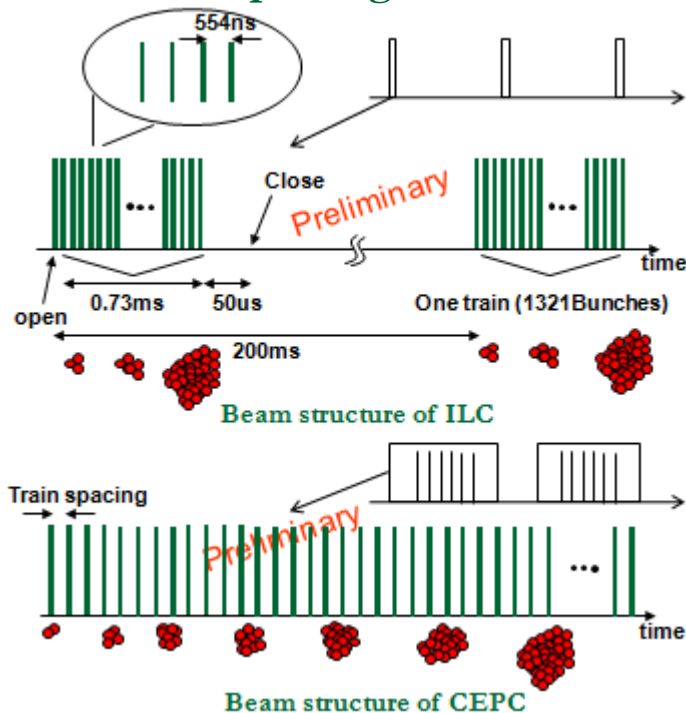


- ❑ Duration of measurement time: 20mins
- ❑ Average of the energy: 46.53μJ/Φ5mm
- ❑ Stability of the laser beam energy: 3.3%



# Distortion by UV+Laser

- ❑ To mimic the bunch structure & the ions distortion with UV light and laser split beam
- ❑ In the case of CEPC-TPC
  - Bunch-train structure of the CEPC
- ❑ In the case of ILD-TPC
  - Bunch-train structure of the ILC
  - Power pulsing mode



Shutter time similar to ILC and CEPC beam structure

- 
- Low power consumption ASIC FEE chip R&D
    - 65 nm CMOS process
    - 5mW/ch with ADC

# ASIC FEE ASIC chips

- Current TPC readout ASICs

|                    | PASA/ALTRO            | AFTER                   | Super-ALTRO           | SAMPA                 |
|--------------------|-----------------------|-------------------------|-----------------------|-----------------------|
| TPC                | ALICE                 | T2K                     | ILC                   | ALICE upgrade         |
| Pad size           | 4x7.5 mm <sup>2</sup> | 6.9x9.7 mm <sup>2</sup> | 1x6 mm <sup>2</sup>   | 4x7.5 mm <sup>2</sup> |
| Pad channels       | 5.7 x 10 <sup>5</sup> | 1.25 x 10 <sup>5</sup>  | 1-2 x 10 <sup>6</sup> | 5.7 x 10 <sup>5</sup> |
| Readout Chamber    | MWPC                  | MicroMegas              | GEM/MicroMegas        | GEM                   |
| Analog Front-end   |                       |                         |                       |                       |
| Gain               | 12mV/fC               | 18 mV/fC                | 12-27 mV/fC           | 20/30 mV/fC           |
| Shaper             | CR-(RC) <sup>4</sup>  | CR-(RC) <sup>2</sup>    | CR-(RC) <sup>4</sup>  | CR-(RC) <sup>4</sup>  |
| Peaking time       | 200 ns                | 100 ns                  | 30-120 ns             | 80/160 ns             |
| ENC                | 385 e                 | 1000 e                  | 520 e                 | 482 e @ 180ns         |
| Waveform Sampler   |                       |                         |                       |                       |
| Method             | ADC                   | SCA                     | ADC                   | ADC                   |
| Sampling frequency | 10MSPS                | 25MSPS                  | 40MSPS                | 20MSPS                |
| Dynamic range      | 10bit                 | 10bit                   | 10bit                 | 10bit                 |
| Power consumption  | 32mW/ch               | 6.2-7.5mW/ch            | 47.3mW/ch             | 8mW/ch                |
| CMOS Process       | 250 nm                | 350 nm                  | 130 nm                | 130nm                 |



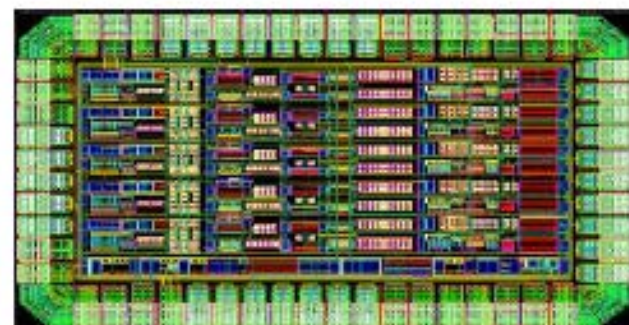
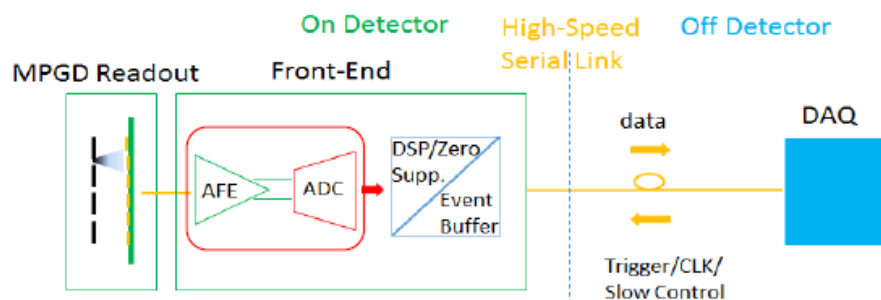
# ASIC FEE requirements

- Requirement for the front-end electronics
  - Analog front-end, including preamplifier and shaper
  - Waveform sampling ADC in 10b and 20-40MSPS
  - Continuous working, no power pulsing → Low power consumption

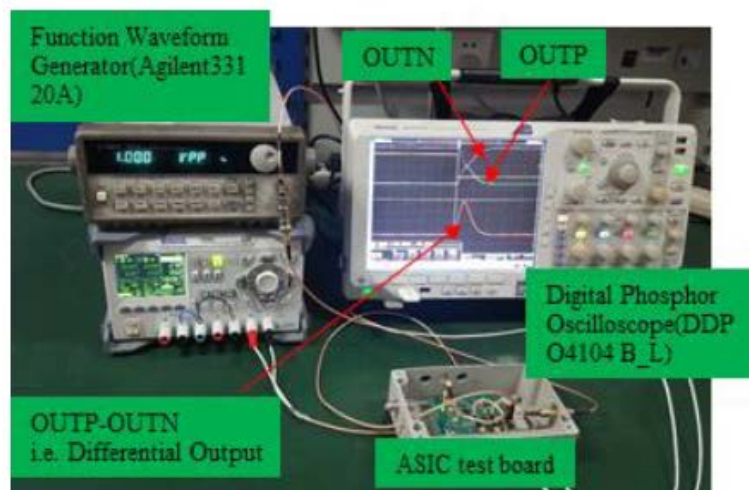
| Total number of channels |               | ~1 Million per endcap                          |
|--------------------------|---------------|------------------------------------------------|
| AFE                      | ENC           | 500 e                                          |
|                          | Gain          | 10 mV/fC                                       |
|                          | Peaking time  | 160 ns                                         |
| ADC                      | Sampling rate | 20-40 MSPS                                     |
|                          | Resolution    | 10 bit                                         |
| Buffer latency           |               | ~50 $\mu$ s                                    |
| Data readout rate        |               | 20 Gb per event w.o. zero compression          |
| Power consumption        |               | <10 mW per channel                             |
| Area                     |               | < 6 mm <sup>2</sup> per channel, incl. cooling |

# ASIC FEE R&D

- Develop a low power and highly integration front-end ASIC in 65 nm CMOS
- Each channel consists of the analog front-end (AFE) and a SAR ADC in 10b and up to 40 MSPS
- Less than 5 mW per channel



1320um x 838um



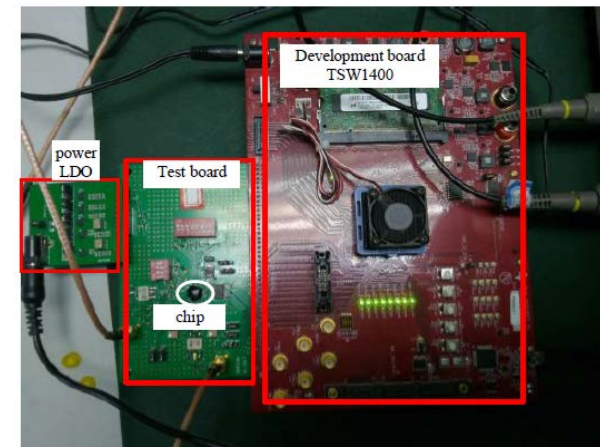
# Preliminary of ASIC FEE R&D

- AFE test summary

|                   | Specifications | Test Results |
|-------------------|----------------|--------------|
| Gain              | 10mV/fC        | 10.5mV/fC    |
| Dynamic Range     | 120fC          | >120fC       |
| INL               | <1%            | 0.41%        |
| Power consumption | 2.50mW/ch      | 2.18mW/ch    |
| ENC               | 500e @ 10pF    | 448e @ 10pF  |
| Xtalk             | <1%            | <0.36%       |

- SAR ADC test summary

|                   | Specifications | Test Results |
|-------------------|----------------|--------------|
| Sampling rate     | 40 MSPS        | 50 MSPS      |
| Resolution        | 10 bit         | 10 bit       |
| INL               | <0.65 LBS      | <0.5 LSB     |
| DNL               | <0.6 LSB       | <0.5 LSB     |
| ENOB              | >9 bit         | 9.18 bit     |
| Power consumption | <2.5 mW/ch     | 1 mW/ch      |



- Test setup
  - TSW1400EVM

# Manpower and future plan

- ❑ **TPC detector module and prototype R&D @IHEP**
  - ❑ Huirong Qi
  - ❑ Haiyun Wang(PhD,IHEP), Zhiyang Yuan(PhD,IHEP), Ling Liu (Master,IHEP)
  - ❑ Prof. Ouyang Qun, Prof. Jin Li
  - ❑ Funding from MOST and NSFC
  
- ❑ **FEE Electronics R&D &Tsinghua**
  - ❑ Zhi Deng
  - ❑ Yiming Cai(PhD,THU), Zhao Mingrui (Master, THU) and three PhDs in electronics lab
  - ❑ Prof. Yuanning Gao, Prof. Yulan Li
  - ❑ Funding from NSFC

# Summary

## TPC detector module and prototype R&D

- ❑ **No Gating device options used for Higgs/Z pole run**
- ❑ **Continuous Ion Back Flow due to the continuous beam structure (Developed in IHEP)**
- ❑ **Preliminary results: Key factor of  $IBF \times Gain = 5$**
- ❑ **Low discharge and spark possibility**
- ❑ **TPC prototype with the laser calibration system**

**Low power front-end ASICs have been developed to meet the stringent requirements of CEPC TPC readout by**

- ❑ **Using advanced 65 nm CMOS process**
- ❑ **Adopting circuit structure with minimized analog circuits such CR-RC shaper and SAR ADC**

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**Thanks.**